



DEFENSE LOGISTICS AGENCY  
LAND AND MARITIME  
POST OFFICE BOX 3990  
COLUMBUS, OH 43218-3990

June 9, 2011

Ms. Lucy Garvin  
DDi Toronto Corp.  
8150 Sheppard Avenue East  
Scarborough, Ontario  
Canada, M1B 5K2

Dear Ms. Garvin:

RE: Notification of Add-On Qualifications, MIL-PRF-31032, FSC 5998, CAGE Code 3AF82;  
VQ(VQE-11-022676)

Add-on qualification for your products is granted under the current issue of the specification as a result of successful add-on qualification testing to Department of Defense Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specifications MIL-PRF-31032/1 and /2. The material and classification indicated below shall be listed on Qualified Manufacturers List QML-31032 (changes are highlighted). The effective date of this qualification is June 9, 2011.

MIL-PRF-31032/1, /2	
Panel Size	18" X 24"
Max. Board Thickness	.088"
Cu Foil Weight	¼ oz. to 2 oz.
Max/Min Plated Hole Size	/.0098" (drilled, mechanical)
Aspect Ratio	8.4:1
Max. Number of Layers	18
Min. Conductor Width	.0037"
Min. Conductor Spacing	.0028"
Part Mounting	SM, THM, MIX
Base Material	GF (Woven E-Glass, Epoxy Resin)
Finish System	HASL, <b>ENEPIG</b>
Hole Preparation	Chemical Desmear, <b>Plasma Etchback</b>
Copper Plating	Acid Copper (DC Plate)
Solder Resist	LPI
Hole Wall Conductive Coating	Electroless Copper
Controlled Impedance	Characteristic(+/- 10%) Differential (+/- 10%)
Alternate Construction	Blind Vias, Sequential Lamination, Foil Lamination, <b>Buried Vias, Microvias</b>
Hole Fill / Via Plug	Non-conductive Epoxy Hole Fill / Via Plug, <b>Copper Conductive Hole Fill</b>

MIL-PRF-31032/1, /2	
Panel Size	18" X 24"
Max. Board Thickness	.093"
Cu Foil Weight	¼ oz. to 2 oz.
Max/Min Plated Hole Size	/ .0091" (drilled, mechanical)
Aspect Ratio	9.6:1
Max. Number of Layers	20
Min. Conductor Width	.004"
Min. Conductor Spacing	.003"
Part Mounting	SM, THM, MIX
Base Material	GI (Woven E-Glass, Polyimide Resin)
Finish System	HASL
Hole Preparation	Chemical Desmear, Plasma Etchback
Copper Plating	Acid Copper (DC Plate)
Solder Resist	LPI
Hole Wall Conductive Coating	Electroless Copper
Controlled Impedance	Characteristic (+/- 10%) Differential (+/- 10%)
Alternate Construction	Blind Vias, Sequential Lamination, Foil Lamination, Buried Vias, Microvias
Hole Fill / Via Plug	Non-conductive Epoxy Hole Fill / Via Plug, Copper Conductive Hole Fill

Test report number 31032-3268-10 has been assigned to your test data. These qualifications are based on your MIL-PRF-31032 certification and are subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.

5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Lowell Sherman at [vqe.ls@dla.mil](mailto:vqe.ls@dla.mil) or 614-692-0627.

Sincerely,

/SIGNED/

JOSEPH GEMPERLINE  
Chief  
Sourcing and Qualifications Division

cc:  
NDQAR Ont-Prairies